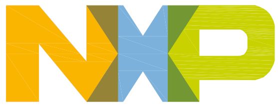

DETAIL G

PIN 1 INDEX 0.80 DIA.

4X 0.10 C B

4X 0.10 C A

DETAIL F PIN 1 INDEX HALF-MOON OPTION

DETAIL F PIN 1 INDEX

56X 0.5

56X 0.30 / 0.18

56X 0.50 / 0.30

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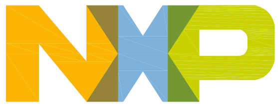
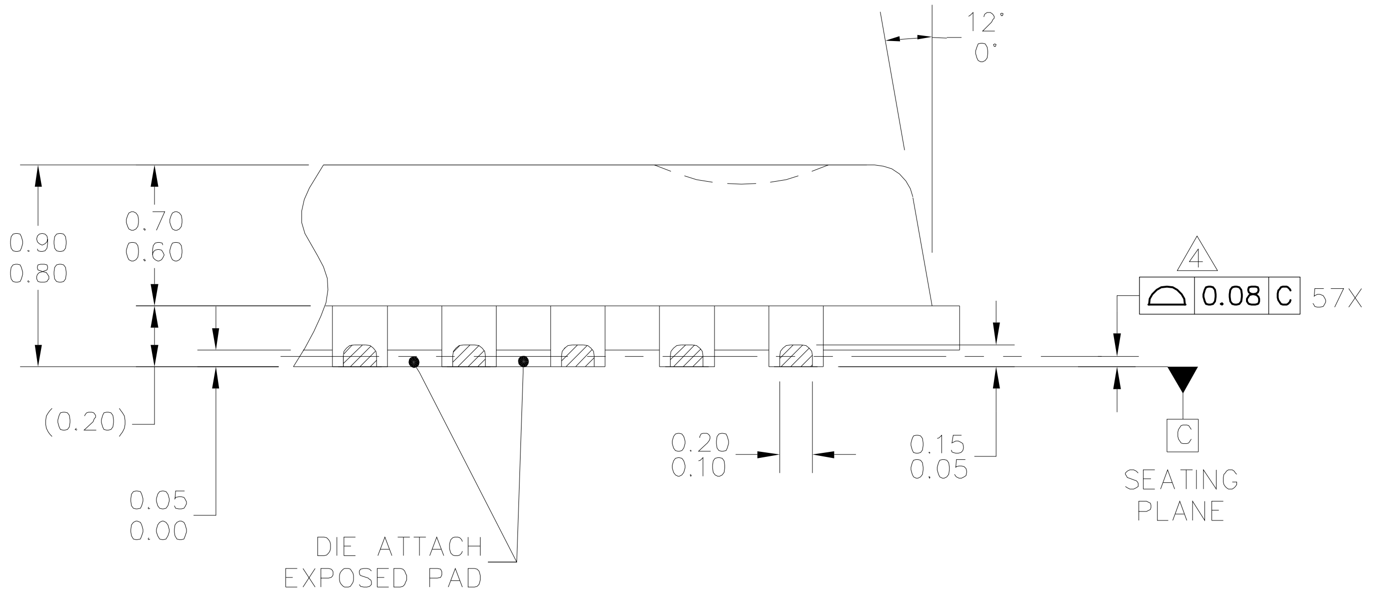
TITLE: QFN (PUNCH), THERMALLY ENHANCED, WETTABLE FLANKS, 8 X 8 X 0.85, 0.5 PITCH, 56 TERMINAL	DOCUMENT NO: 98ASA00379D	REV: F
	STANDARD: NON-JEDEC	
	SOT684-15	08 JAN 2016





DETAIL G
VIEW ROTATE 90° CW

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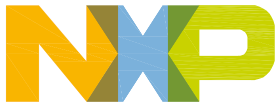
	STANDARD: NON-JEDEC
	SOT684-15 08 JAN 2016



2X 4.488

2X 3.44

2X 3.625

PIN #1 IDENTIFIER

2X 4.488

2X 3.44

4X 1.963

2X 3.925

4X 0.925

PACKAGE OUTLINE

4X 6.88

PCB DESIGN GUIDELINES – SOLDER MASK OPENINGS

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL / SPECIFIC REQUIREMENTS.

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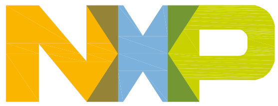

0.25

4X 4.425

2X 1.3

52X 0.5

PIN #1 IDENTIFIER

2X 1.4

9X 1

56X 0.25

PACKAGE OUTLINE

9X 0.9

56X 0.85

PCB CU GUIDELINES — I/O PADS & SOLDERABLE AREAS

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL / SPECIFIC REQUIREMENTS.

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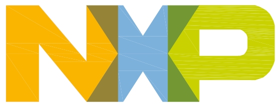
	STANDARD: NON-JEDEC	
	SOT684-15	08 JAN 2016



0.25

2X 4.35

52X 0.5

2X 1.3

PIN #1 IDENTIFIER

2X 1.4

9X 0.75

56X 0.225

PACKAGE OUTLINE

9X 0.75

56X 0.7

SOLDER PASTE STENCIL DESIGN GUIDELINES

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL / SPECIFIC REQUIREMENTS.

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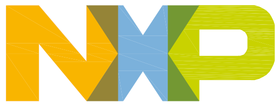

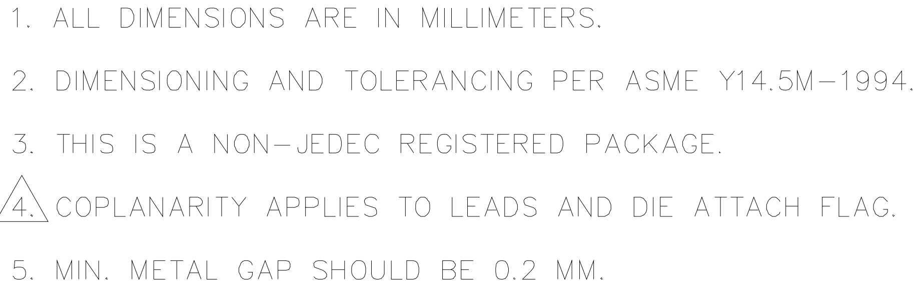

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M−1994.

3. THIS IS A NON−JEDEC REGISTERED PACKAGE.

4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.

5. MIN. METAL GAP SHOULD BE 0.2 MM.

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